AMENDMENTS TO THE CLAIMS

1. (Previously Presented) A method for manufacturing a flat printed wiring board, including the steps of:

obtaining a printed wiring board with circuit patterns formed on a surface of the printed wiring board;

forming a resin layer by superposing a semi-cured resin sheet having resin patterns formed thereon on the surface of the printed wiring board containing said circuit patterns, the resin patterns formed on the semi-cured resin sheet being the inverse of the circuit patterns formed on the printed wiring board;

pressing and forcing the resin layer into spaces between said circuit patterns;

curing said resin layer; and

polishing said cured resin layer, thereby exposing said circuit patterns,

wherein said resin patterns on said semi-cured resin sheet are formed before said semi-cured resin sheet is superposed on the surface of the printed wiring board, said resin patterns being formed on a surface of said semi-cured resin sheet facing said circuit patterns.

2. (Canceled)

3. (Previously Presented) The method for manufacturing the flat printed wiring board according to claim 1, wherein the pressing against said resin layer is performed in a reduced pressure atmosphere.

4. (Previously Presented) The method for manufacturing the flat printed wiring board according to claim 3 wherein a metallic foil with a roughened surface facing said resin layer is superposed and pressed on said resin layer.

5. (Previously Presented) The method for manufacturing the flat printed wiring board according to claim 4 wherein said metallic foil is formed with a metal of a different kind than said circuit patterns.

6. (Previously Presented) The method for manufacturing the flat printed wiring board according to claim 5 wherein said metallic foil is formed from a nickel material.

7. (Previously Presented) The method for manufacturing the flat printed wiring board according to claim 6 wherein said semi-cured resin sheets are formed from a thermosetting epoxy resin.

8. (Previously Presented) The method for manufacturing the flat printed wiring board according to claim 6 wherein said semi-cured resin sheets are formed from a thermosetting resin.

9-19. (Canceled)

20. (Currently Amended) The method for manufacturing the flat printed wiring board according to claim 1 wherein said circuit patterns are formed by a photo etching ~~subtractive~~ method.